

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------|------------------|---------|------------------|
| L2 | 72 | (first near2 (chip die device semiconductor)) with (adhesive underfill (under adj fill)) with (inject\$3 introduc\$3) with between | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/05/14 11:57 |
| L5 | 1409 | (inject\$3 introduc\$3) with (underfill (under adj fill) adhesive (bonding adj (material paste resin))) with (push\$3 away forc\$3) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/05/14 13:42 |
| L6 | 1 | 5 with (first near2 (chip die device semiconductor)) with (second near2 (chip die device semiconductor)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/05/14 13:43 |
| L7 | 3628 | ((inject\$3 introduc\$3) with (underfill (under adj fill) adhesive (bonding adj (material paste resin)))) same (push\$3 away forc\$3) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/05/14 14:04 |
| L8 | 11 | 7 same ((first near2 (chip die device semiconductor)) with (second near2 (chip die device semiconductor))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/05/14 14:04 |
| L12 | 7111 | ((inject\$3 dispens\$3 introduc\$3) with (underfill (under adj fill) adhesive (bonding adj (material paste resin)))) same (push\$3 away forc\$3) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/05/14 14:04 |
| L13 | 48 | 12 same (second near2 (chip die device semiconductor)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/05/14 14:05 |